

Toggle Switches

Sub-Miniature

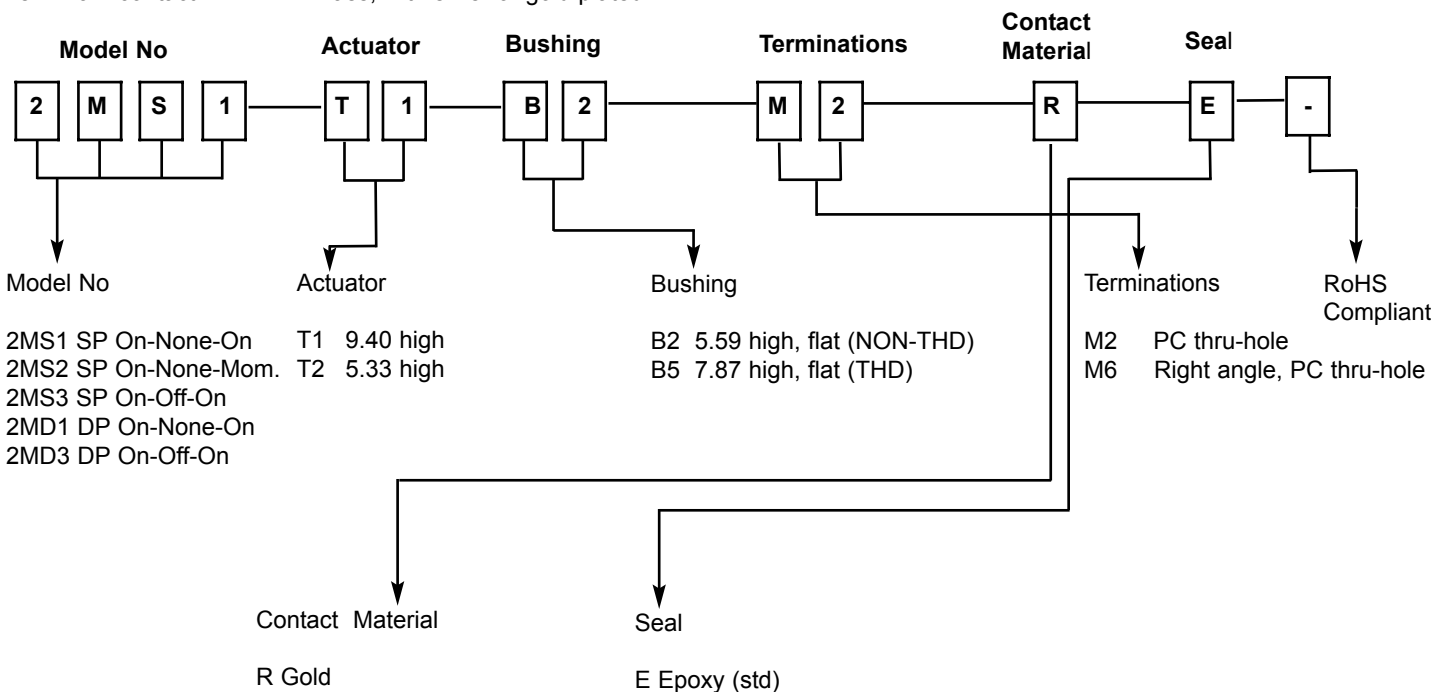


Specifications:

Contact rating	: Dependent upon contact material.
Mechanical life	: 30,000 make-and-break cycles.
Maximum contact resistance	: 20mΩ initial at 2-4V dc 100mA for both silver and gold plated contacts.
Minimum Insulation resistance:	: 1,000MΩ.
Dielectric strength	: 1,000V rms at sea level.
Operating temperature	: -30°C to 85°C.

Materials:

Case	: Diallyl phthalate (DAP).
Actuator	: Brass, chrome plated.
Bushing	: Brass, nickel plated.
Housing	: Stainless steel.
Switch support	: Brass, tin plated.
Terminal / contact	: Brass, with silver or gold plated.



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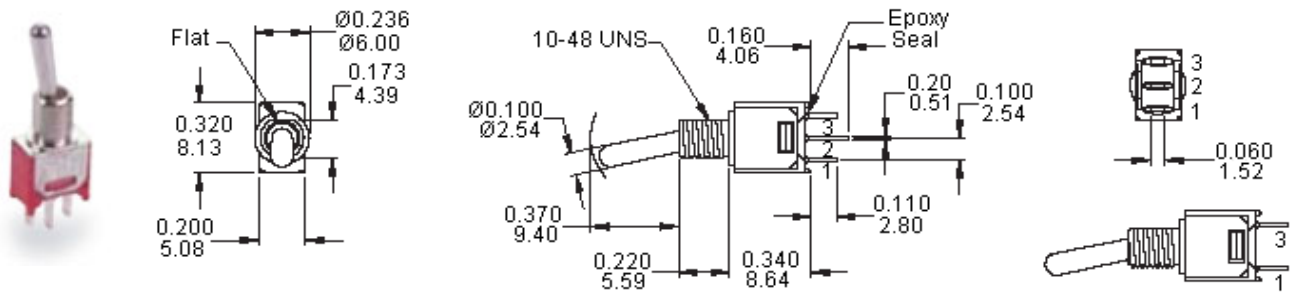
Switch Function

Number of Poles	UL/CSA Model Number	Model Number	Switch Function			Connected Terminals / Schematic		
			Position 1	Position 2	Position 3	Position 1	Position 2	Position 3
SP	Q2211	2MS1	On	None	ON	2-3 2 (Comm)	N/A	2-1
	Q2212	2MS2			MOM			1-2 (Comm)
	Q2213	2MS3			Off			1-3
DP	Q2221	2MD1	On	None	ON	2-3, 5-6 2 (Comm) 5	N/A	2-1, 5-4
	Q2223	2MD3						Off

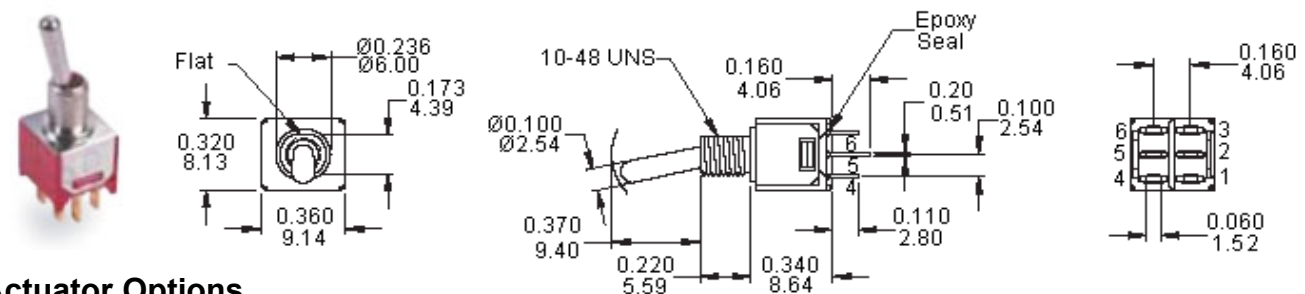
MOM = Momentary

Pole Options

SPDT

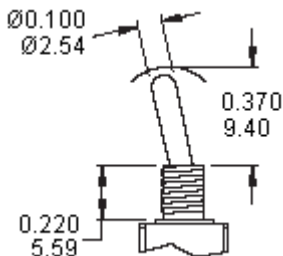


DPDT

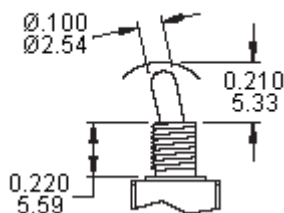


Actuator Options

T1



T2



T1, T2, Actuator shown with B2 bushing, subtract 0.09 (2.29) for B5 bushing, subtract 0.04 (1.02) for B5 bushing, add 0.09 (2.29) Std for M2 terminal sub 0.016 (0.040) for M2 terminals sub. 0.016 (0.040) for M6.

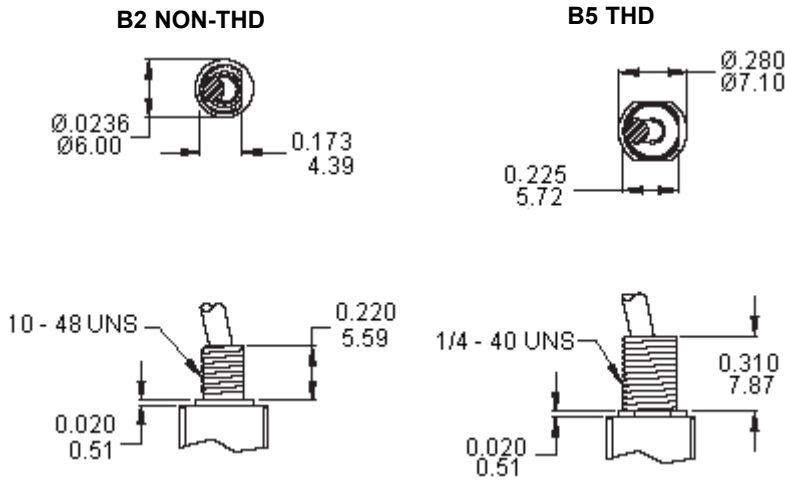


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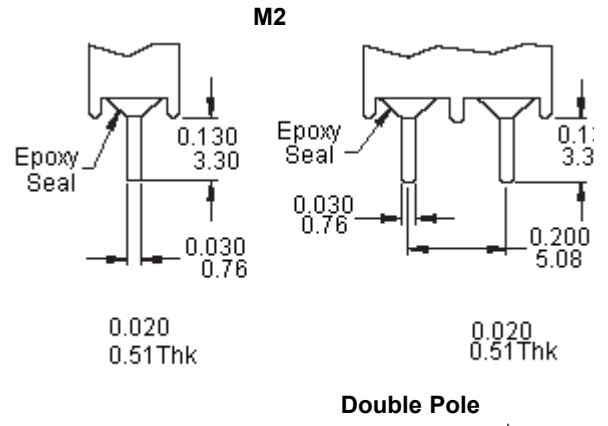
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Bushing Options

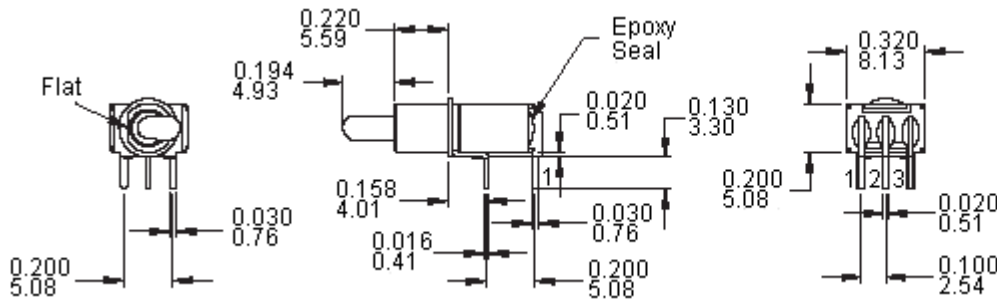


Termination Option

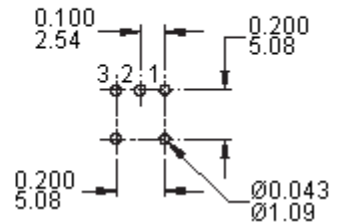


Termination Options

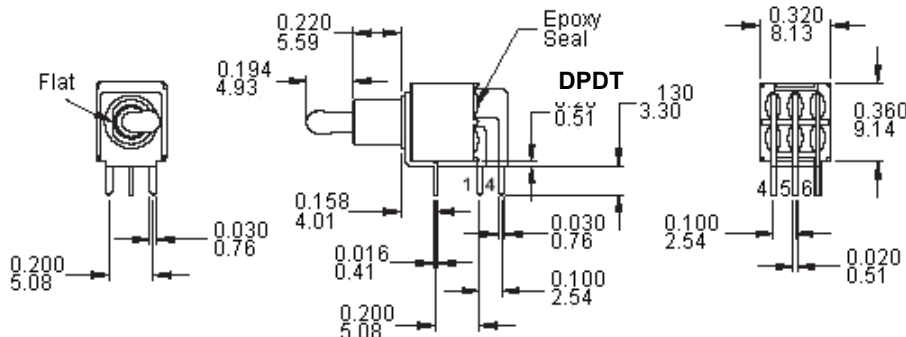
M6, SPDT



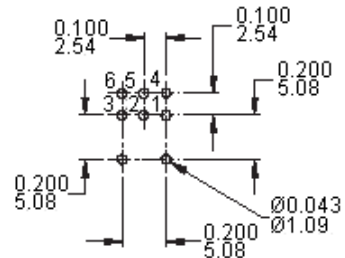
P. C. Mounting



M6, DPDT



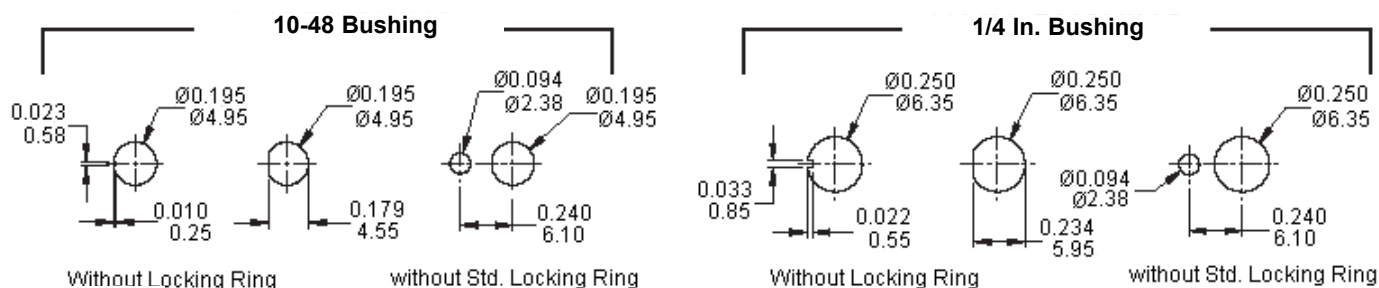
P. C. Mounting



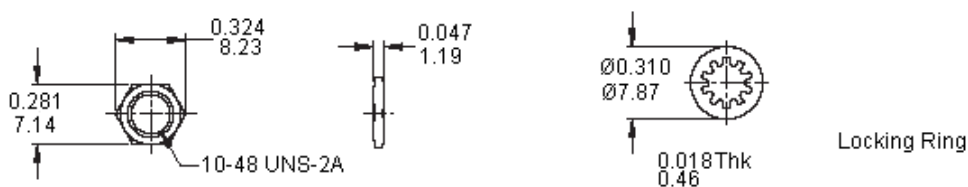
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Panel Mounting



Hardware



Contact Material Options

	Contact Plating	Terminal Plating	Ratings
R	Gold	R = Gold	0.4 Volt - Amperes (VA) maximum at 20V maximum (AC or DC)

Soldering Process:

Manual soldering	: Use soldering iron of 30 watts, controlled at 350°C approximately 5 seconds while applying solder.
Wave soldering	: Recommended soldering temperature : 260 ±5°C. : Duration of solder immersion : Maximum 5 seconds (PCB is 1.6mm in thickness).

Soldering : Vapour phase

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